

Description

TSS Series are designed to protect baseband equipment such as modems, line cards, CPE and DSL equipments from damaging overvoltage transients. The series provide a robust peak surge current capability which enables equipments to comply with global regulatory standards.

Features

- Low voltage overshoot
- Low on-state voltage
- Low capacitance
- Low leakage current
- High reliability
- Quick response to surge voltage (ns Level)
- Does not degrade in capability after multiple surge events within limit.
- Low capacitance
- Fails short circuit when surged in excess of ratings

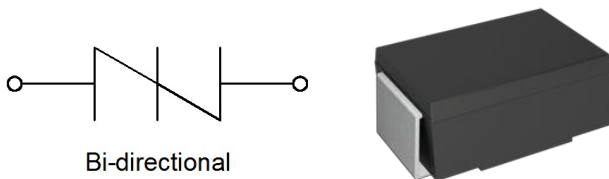
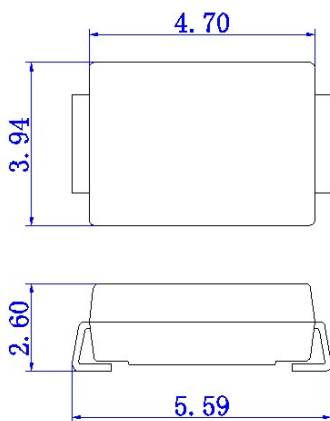
Applications

- Audio/Video line
- Network and telecom
- Data lines and security systems
- Serial ports

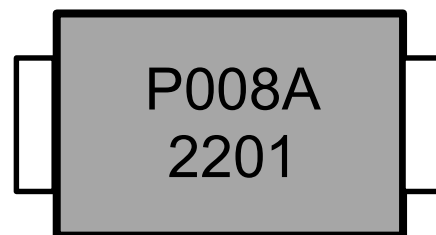
Mechanical Characteristics

- Package: SMA/DO-214AC
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0 .RoHS compliant
- Moisture Sensitivity: Meet MSL 1
- Terminal: Solder plated, solderable per MIL-STD-750, Method 2026
- Polarity: Color band denotes cathode except bi-directional models
- Weight: 0.09g(approximate)

Dimensions & Symbol (Unit: mm Max)



Marking Information



P008A: P0080TA Marking Code (Others See blow)
2201: Date code(2022 year, 01 week)

Electrical Characteristics (T=25°C)

Part Number	Marking Code	I _{DRM} @V _{DRM}		V _S @I _S		V _T @ I _T		I _H	C _O
		μA	V	V	mA	V	A	mA	pF
		max	min	max	max	max	max	min	max
P0080TA	P008A	5	6	25	800	4	2.2	20	30

Notes:

- All measurements are made at an ambient temperature of 25°C. I_{PP} applies to -40°C through +85°C temperature range.
- Off-state capacitance (C_O) is measured at 1 MHz with a 2 V bias and is typical val

Absolute Maximum Ratings($T=25^{\circ}\text{C}$, $\text{RH}=45\%-75\%$, unless otherwise noted)

Parameter	Symbol	Value	Unit
Operating junction temperature range	T_j	-40 to +125	$^{\circ}\text{C}$
Storage temperature range	T_{stg}	-65 to +150	$^{\circ}\text{C}$
Repetitive peak pulse Voltage(10/700uS)	V_{PP}	2000	V

Typical Characteristics

FIG1: V-I cure characteristics

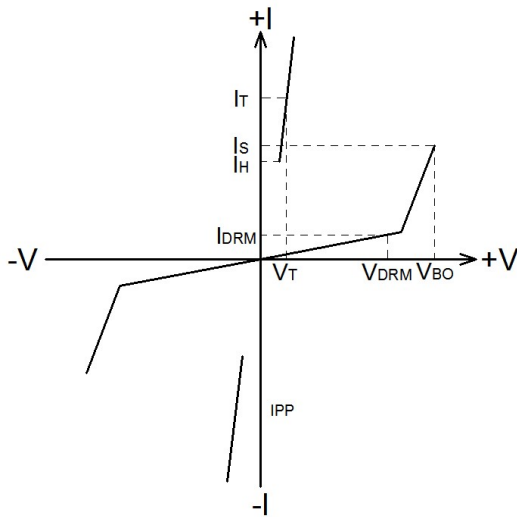


FIG2: Pulse Waveform

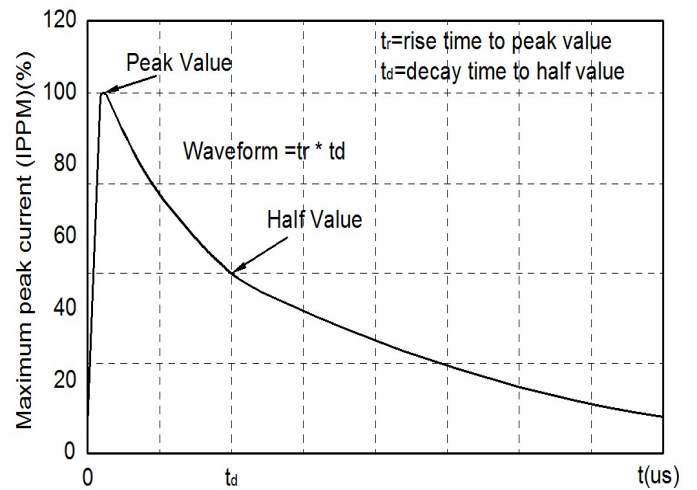


FIG3: Normalized Vs change vs.junction temperature

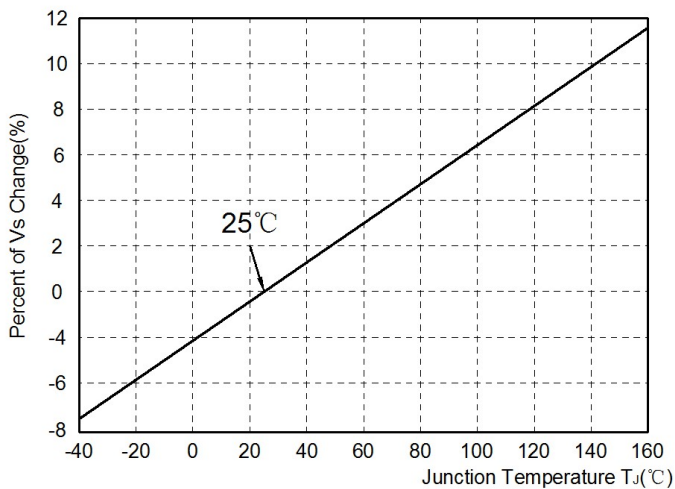
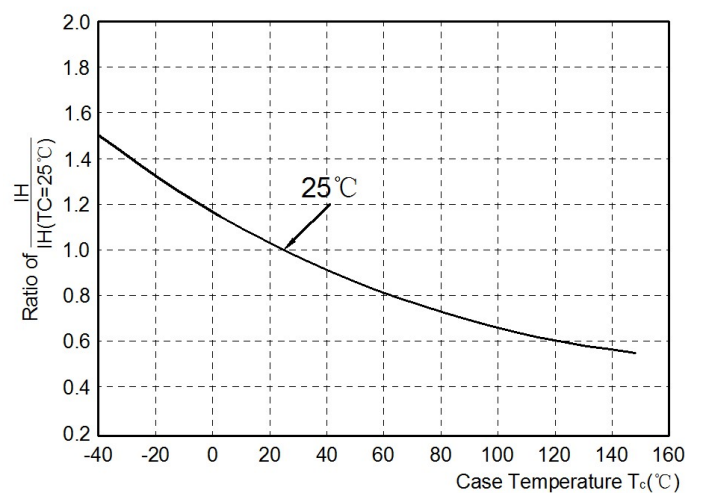
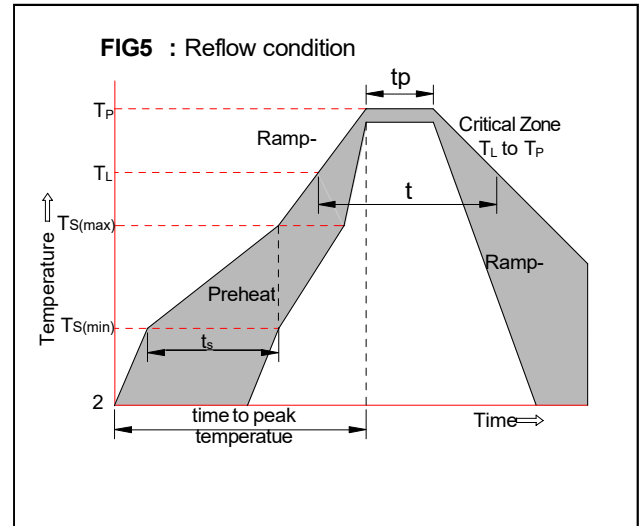


FIG4: Normalized DC holding current vs.case temperature

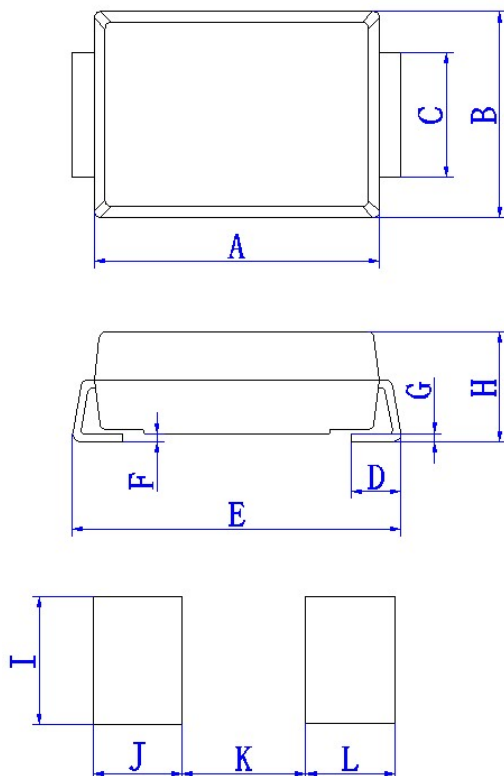


Soldering parameters

Reflow Condition		Pb-Free assembly (see as below)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150°C
	-Temperature Max($T_{s(max)}$)	+200°C
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquid us Temp (T_L) to peak)		3°C/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/sec. Max
Reflow	-Temperature(T_L)(Liquid us)	+217°C
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)°C
Time within 5°C of actual Peak Temp (t_p)		30 secs. Max
Ramp-down Rate		6°C/sec. Max
Time 25°C to Peak Temp (T_p)		8 min. Max
Do not exceed		+260°C



Package mechanical data



Ref.(mm)	Millimeters	
	Min.	Max.
A	3.99	4.50
B	2.50	2.90
C	1.20	1.70
D	0.76	1.52
E	4.93	5.28
F	0	0.20
G	0.15	0.25
H	1.98	2.41
I	1.50	1.70
J	1.40	1.60
K	2.30	2.50
L	1.40	1.60